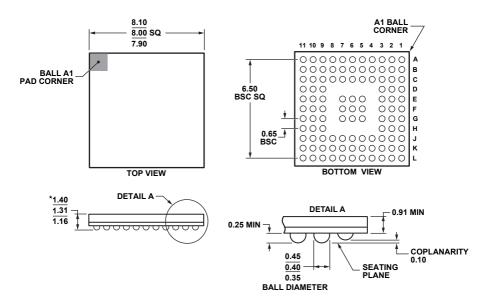


105-Ball Chip Scale Package Ball Grid Array [CSP_BGA] (BC-105-1) Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-225 WITH THE EXCEPTION TO PACKAGE HEIGHT.

BC-105 REV A 0.65 ≤ 181 0.50 dia[×] $\equiv 0.65$ (Dim. are in MM) LAST MODIFIED 03/06/07

Analog Devices